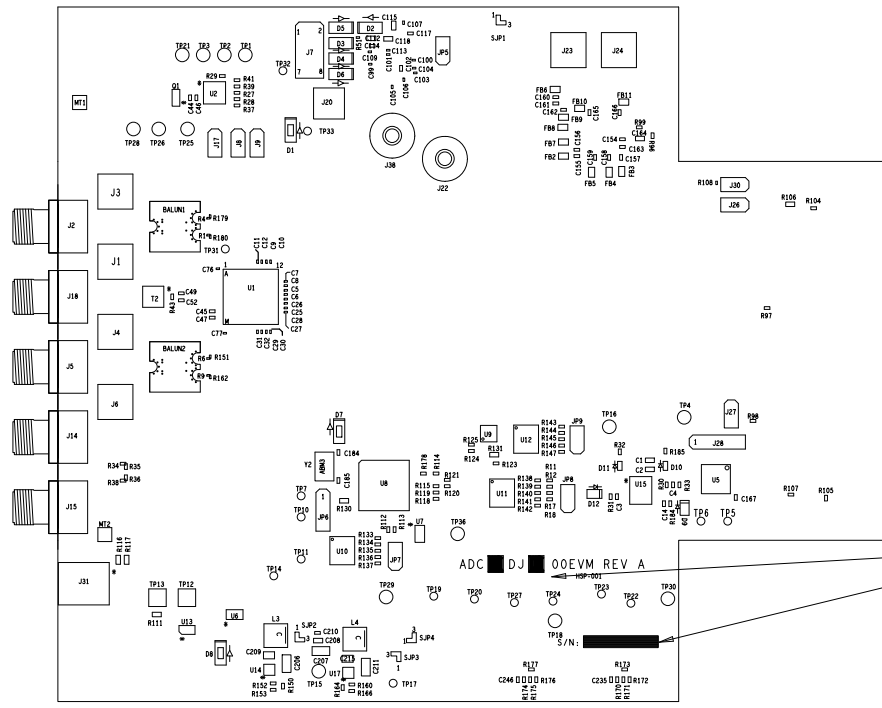


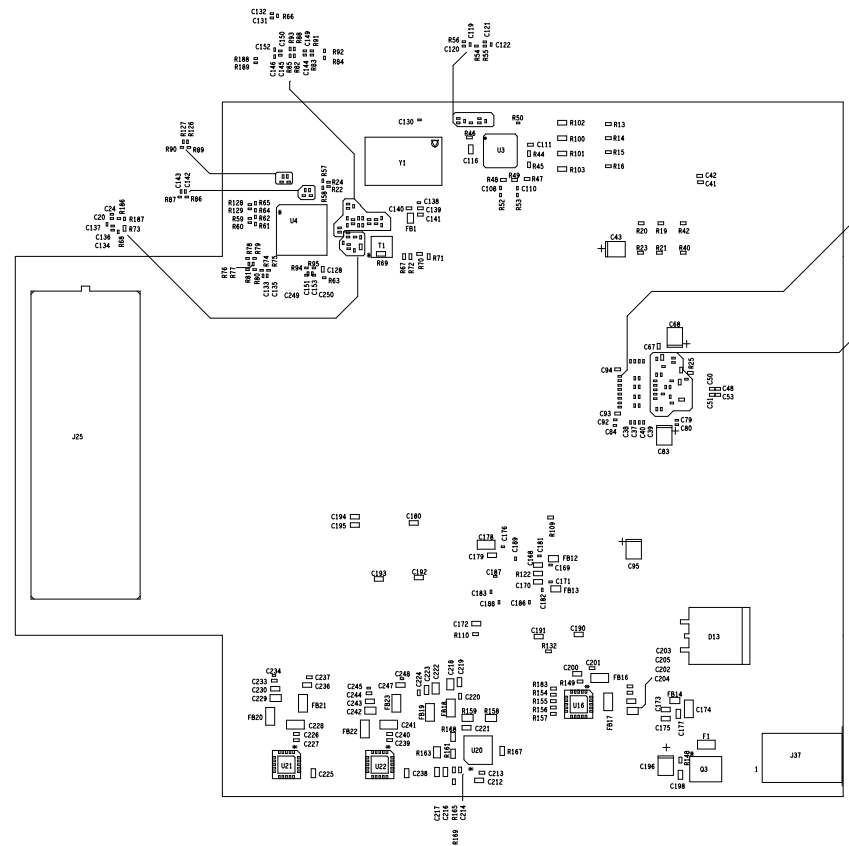
THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY. ASSEMBLY MUST BE RoHS COMPLIANT AND LEAD FREE.
3. MARK BOARD'S SILKSCREEN WITH THE APPROPRIATE EVM PART NUMBER AND SERIAL NUMBER.
4. IPC-A-610 / ACCEPTABILITY OF ELECTRONIC ASSEMBLIES, CLASS2, CURRENT REVISION.

ZONE		REVISIONS		DATE	APPROVED
ZONE	LTR	DESCRIPTION			



TOP VIEW



BOTTOM VIEW

SEE NOTE 3

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE		
MATERIAL SEE NOTE 5	DRAWN	JV SMITH	ASSEMBLY DRAWING ADC12DJ3200 EVM	
	ENGR	J BRINKHURST		
FINISH SEE NOTES 7, 8, 9			SIZE	REV.
	DO NOT SCALE DRAWING		B	A
		SCALE	2:1	SHEET 1 OF 1

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